



Semiconductor Device Type: SCX UQFN-36-5x5x0.6mm-MatteTin						Package Homogeneous Materials				
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	3.60	(mg) Total	Die	% of Total Weight	7.78
Silicon	7440-21-3	Die	7.78	3.60	77754			Silicon	7440-21-3	100.00
Magnesium	7439-95-4	Leadframe	0.05	0.02	518			Total 100.00		
Silicon	7440-21-3	Leadframe	0.23	0.11	2311					
Nickel	7440-02-0	Leadframe	0.99	0.46	9892	14.30	(mg) Total	Leadframe	% of Total Weight	30.89
Copper	7440-50-8	Leadframe	29.15	13.50	291490			Magnesium	7439-95-4	0.17
Plating Silver	7440-22-4	Leadframe	0.46	0.22	4644			Silicon	7440-21-3	0.75
Epoxy Resin	Trade Secret	Die Attach	0.27	0.12	2657			Nickel	7440-02-0	3.20
Phenol Resin	Trade Secret	Die Attach	0.32	0.15	3153			Copper	7440-50-8	94.38
Other	Trade Secret	Die Attach	0.10	0.05	972			Plating Silver	7440-22-4	1.50
(Meta) CopolymerAcrylic	Trade Secret	Die Attach	1.74	0.81	17408			Total 100.00		
Copper	7440-50-8	Bonding Wire	2.03	0.94	20324					
Palladium	2023568	Bonding Wire	0.06	0.03	583	1.12	(mg) Total	Die Attach	% of Total Weight	2.42
Gold	7440-57-5	Bonding Wire	0.00	0.00	43			Epoxy Resin	Trade Secret	10.98
Epoxy Resin 1	Trade secret	Molding Compound	2.23	1.03	22311			Phenol Resin	Trade Secret	13.04
Epoxy Resin 2	Trade secret	Molding Compound	1.67	0.78	16739			Other	Trade Secret	4.02
Hardener	Trade secret	Molding Compound	2.79	1.29	27905			(Meta) CopolymerAcrylic	Trade Secret	71.96
Catalyst	Trade secret	Molding Compound	0.56	0.26	5572			Total 100.00		
Carbon Black	1333-86-4	Molding Compound	0.17	0.08	1663					
Amorphous silica1	60676-86-0	Molding Compound	44.46	20.59	444644	0.97	(mg) Total	Bonding Wire	% of Total Weight	2.10
Amorphous silica2	7631-86-9	Molding Compound	3.90	1.81	39050			Copper	7440-50-8	97.01
Tin	7440-31-5	External Plating	1.04	0.48	10367			Palladium	2023568	2.78
46.30 mg Total Mass								Gold	7440-57-5	0.21
TOTALS: 100.00 46.30 1,000,000								Total 100.00		
						25.83	(mg) Total	Molding Compound	% of Total Weight	55.79
								Epoxy Resin 1	Trade secret	4.00
								Epoxy Resin 2	Trade secret	3.00
								Hardener	Trade secret	5.00
								Catalyst	Trade secret	1.00
								Carbon Black	1333-86-4	0.30
								Amorphous silica1	60676-86-0	79.70
								Amorphous silica2	7631-86-9	7.00
								Total 100.00		
						0.48	(mg) Total	External Plating	% of Total Weight	1.04
								Tin	7440-31-5	100.00
						46.30	Total	100.00		100.00

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